

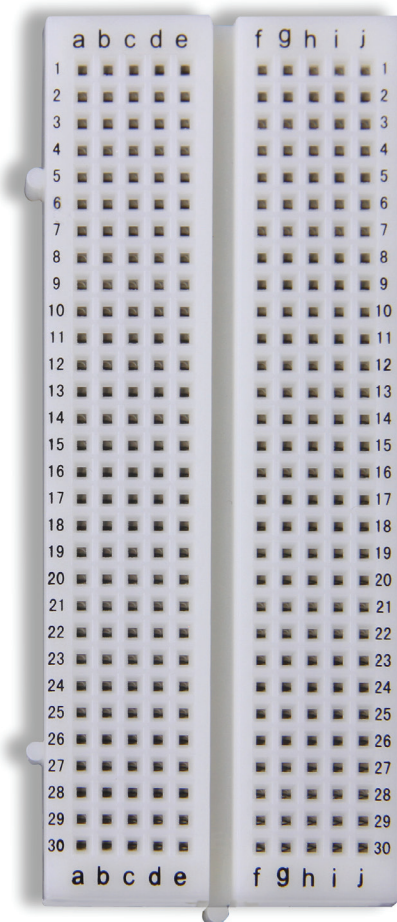
GS-300

300 TIE-POINT, SOLDERLESS BREADBOARD

Applications

The GS-300 is a modular type solderless breadboard that connects with the GS-050 bus strip to make a 400 tie point breadboard (GS-400). Expandable in two dimensions, it is a great way to prototype low frequency or DC powered circuits. They are ideal for:

- Educational labs
- Hobbyists



Features

- 300 Tie-points
- ABS plastic body
- Square hole style
- Interlocking tabs
- Peel and stick adhesive
- Nickel plated phosphor bronze spring clip contacts
- Allowable wire diameter of 0.4-0.7 mm
- Fits 3 total 16-pin ICs
- Measures 3.7 x 8.6 x 1.0 cm
- Weighs 22 g
- Maximum capacity of 1.5 A at 36 V
- RoHS compliant
- Three-year warranty

GS-300

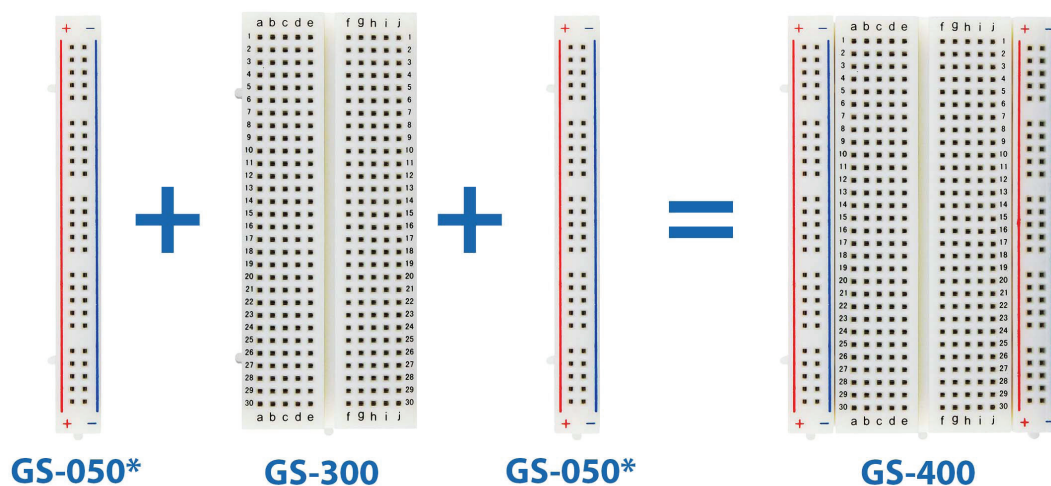
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GS-400 Components



*The GS-050 is sold as a pack of two